

SCHOTT® 25G DML TEC TO Header

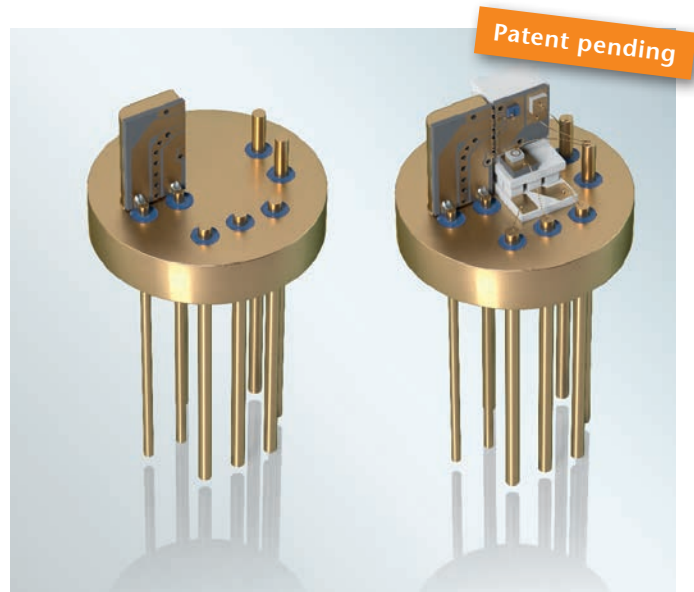
The high-speed, miniaturized, and economical alternative to box packages

Product Information

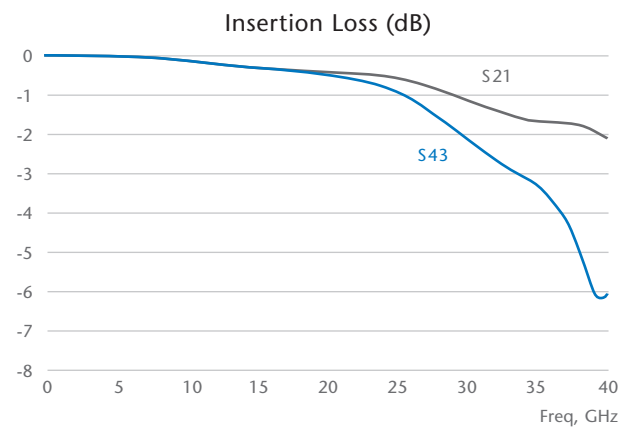
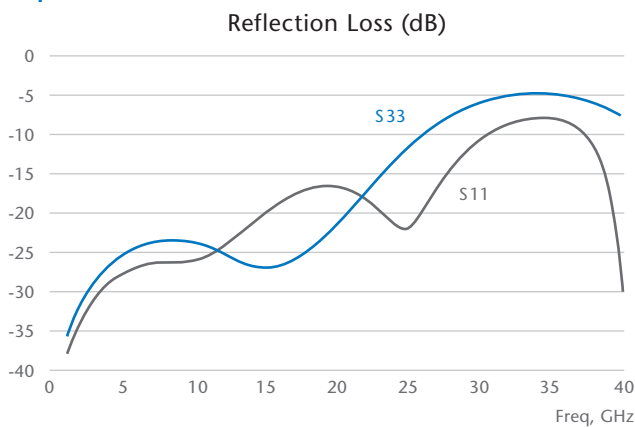
The SCHOTT® 25G DML TEC TO is a transistor outline header platform that opens up new possibilities to replace box packages in actively-cooled high-speed applications, including single-channel 25G CPRI, next-generation PON OLT Tx, and other tunable laser applications. Due to high speed and heat dissipation requirements, complex flat packs or ceramic packages were previously needed to house these DFB lasers. SCHOTT's high-performance TEC TO innovation now enables the use of smaller, more economical transistor outline platforms.

Advantages

- **Excellent RF Performance:** The unique header design is capable of 25 GBit/s data rates thanks to a submount with 25ohm impedance G-S-G-S-G traces, and low reflection and insertion losses.
- **Stable laser wavelengths through improved heat dissipation:** The innovative TEC (thermoelectric cooler) design allows controlled heat dissipation, enabling regulated and stable laser wavelengths. Heat dissipation properties can be further improved with high thermal conductivity materials (e.g. Cu, CuW) for the heat sink.

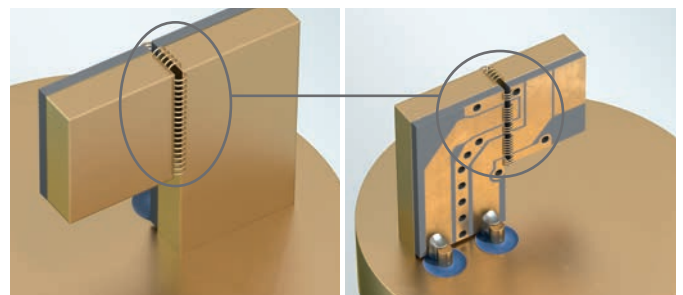


RF performance



Further optimization of RF performance through better grounding can be achieved with additional wire bonding from pedestal to CuW block:

- S11: Better than -15dB @25GHz for speeds of up to 25 Gbit/s
- S21: -3dB bandwidth better up to 40GHz



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